Amendments to the Specification

Please replace the paragraph beginning on line 23, page 2 with the following paragraph, which corrects a typographical error. Added text is underlined. This amendment is supported by the originally-filed application.

A typical solution will be to fabricate or modify devices to be tested into a standard wafer shape, diameter, and thickness. However, this solution presents several problems. Some devices are not suitable for modification due to size constraints (e.g., an overall thickness will be too great when mounted or otherwise affixed to a suitable carrier substrate). Other devices will sacrifice yield by discarding good devices while attempting to accommodate to a standard wafer size (e.g., a large molded array package (MAP) will lose peripheral devices when the MAP is modified into a wafer form). Still other devices are not compatible with standard vacuum transport tools (such as vacuum end-effectors on robotic transport arms).

Please replace the paragraph beginning on line 4, page 7 with the following paragraph, which corrects a typographical error. Added text is underlined. This amendment is supported by the originally-filed application.

The test ring holder 103 contains two milled or machined recesses 105, 107 (see also FIGs. 2 and 3) and an optional thru-hole 109. Inner and outer dimensions of the first recess 105 are selected to accept the test ring magnet 111. The first recess 105 is sufficiently deep so that a top surface of the test ring magnet, once inserted into the first recess 105, is at a level coplanar with or below a top surface of the second recess 107. A depth of the second recess 107 is

selected so as to keep the non-wafer from device (not shown) at a level coplanar with or slightly above a top surface of the test ring holder 103 once the non-wafer form device is mounted into the low-profile carrier 100. A distance that a non-wafer from device may extend above the top surface of the test ring holder 103 will vary depending upon the height tolerances of a testing or measurement tool. As an example, a mounted non-wafer form device will extend 100 μm to 400 μm above the top surface of the test ring holder 103. The optional thru-hole 109 prevents mounting interference caused by irregularities on a bottom side of the non-wafer form device. Finally, an outer dimension of the test ring cover 113 is selected to fit within the first recess 105 and an inner dimension is selected to slightly overlap the non-wafer from device on at least two sides. For example, a test ring cover with inner dimensions of 8 mm by 10 mm will adequately secure a 10 mm by 10 mm non-wafer form device. The test ring cover 113 may be any ferrous material that is capable of being magnetically attracted to the test ring magnet 111. For example, the test ring cover may be machined from tempered blue spring steel.